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CONFIRMATION NO. 3458

SERIAL NUMBER 10/046,073	FILING DATE 01/16/2002 RULE	C	CLASS 029	1		OUP ART UNIT 3729		ATTORNEY DOCKET NO. Q68028	
APPLICANTS Tomoo Murakami, To	okyo, JAPAN;								
** CONTINUING DATA **********************************									
** FOREIGN APPLICATIONS ************************************									
IF REQUIRED, FOREIGN FILING LICENSE GRANTED ** 02/08/2002									
Foreign Priority claimed yes no			STATE OR	SH	SHEETS TO		ΓAL	INDEPENDENT	
/erified and Allowance Examine Signature Initials			COUNTRY JAPAN	DRA	DRAWING CL 9		IMS	CLAIMS 1	
ADDRESS SUGHRUE MION, PLLC 2100 Pennsylvania Avenue, NW Washington , DC 20037-3213									
TITLE Method of mounting a semiconductor device to a substrate and a mounted structure									
				All Fees 1.16 Fees (Filing)					
FILING FEE FEE	ES: Authority has been given in Paper to charge/credit DEPOSIT ACCOUNT			uT	1.17 Fees (Processing Ext. of time)				
RECEIVED No. 740	for following:	322. 23 7.3333			1.18 Fees (Issue)				
					Other				



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	TA ************************************		07/22/1998					
	CATIONS ************************************	***						
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Foreign Priority claimed 35 USC 119 (a-d) conditions met Verified and Acknowledged yes no Me Allowance Allowance Examiner's Signature		er tials	STATE OR COUNTRY JAPAN	SHEETS DRAWING 9		TOTAL CLAIMS 4		INDEPENDENT CLAIMS 1
ADDRESS SUGHRUE MION, Pl 2100 Pennsylvania A Washington ,DC 200	venue, NW							
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